Title (en)

METHOD FOR PRODUCING A MICROMECHANICAL COMPONENT HAVING A TRENCH STRUCTURE FOR BACKSIDE CONTACT

Title (de)

VERFAHREN ZUR HERSTELLUNG EINES MIKROMECHANISCHEN BAUELEMENTS MIT TRENCHSTRUKTUR ZUR RÜCKSEITENKONTAKTIERUNG

Title (fr)

PROCÉDÉ DE FABRICATION D'UN COMPOSANT MICROMÉCANIQUE COMPORTANT UNE STRUCTURE DE TRANCHÉE DE MISE EN CONTACT SUR LA FACE ARRIÈRE

Publication

EP 2150487 A2 20100210 (DE)

Application

EP 08735959 A 20080408

Priority

- EP 2008054233 W 20080408
- DE 102007019638 A 20070426

Abstract (en)

[origin: WO2008132028A2] The invention relates to a method for producing a micromechanical component. The aim of the invention is to produce at least one trench structure in a substrate, said trench structure having a depth that is less than the substrate thickness. An insulating layer is applied to a first face of the substrate and a filler layer is produced on or applied to the substrate. Said filler layer comprises a filler material that fills the trench structure essentially completely. A planarization within a plane of the filler layer or the insulating layer or the substrate produces a planar first face of the substrate. Subsequently, the second face of the substrate is planarized. The invention also relates to a micromechanical component which is produced according to said method.

IPC 8 full level

B81B 7/00 (2006.01)

CPC (source: EP US)

B81C 1/00095 (2013.01 - EP US); **H01L 21/76898** (2013.01 - EP); **H01L 23/481** (2013.01 - EP)

Citation (search report)

See references of WO 2008132028A2

Citation (examination)

US 2002167072 A1 20021114 - ANDOSCA ROBERT GEORGE [US]

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MT NL NO PL PT RO SE SI SK TR

Designated extension state (EPC)

AL BA MK RS

DOCDB simple family (publication)

DE 102007019638 A1 20081030; EP 2150487 A2 20100210; JP 2010526672 A 20100805; JP 5383657 B2 20140108; US 2010133630 A1 20100603; US 2012049301 A1 20120301; US 8138006 B2 20120320; US 8564078 B2 20131022; WO 2008132028 A2 20081106; WO 2008132028 A3 20090108

DOCDB simple family (application)

DE 102007019638 A 20070426; EP 08735959 A 20080408; EP 2008054233 W 20080408; JP 2010504610 A 20080408; US 201113291350 A 20111108; US 59713708 A 20080408